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RESPONSE UNDER 37 C.F.R. § 1.116
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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|-------------|---|-------------|-----------------|
| Applicant: | Thomas, et al. | Docket No.: | 2003 P 54322 US |
| Serial No: | 10/790,907 | Art Unit: | 2822 |
| Date Filed: | March 2, 2004 | Examiner: | Au, Bac H. |
| Title: | Integrated Circuit with Re-Route Layer and Stacked Die Assembly | | |

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- Certification of Facsimile Transmission (1 page)
- Response under 37 CFR § 1.116 (16 pages)

Respectfully submitted,

Theresa L. O'Connor
Legal Assistant

Confirmation Respectfully Requested

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Serial No.: 10/790,907 Art Unit: 2822
Filed: March 2, 2004 Examiner: Au, Bac H.
For: Integrated Circuit with Re-Route Layer and Stacked Die Assembly

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE UNDER 37 CFR § 1.116

Dear Sir:

Applicants respectfully submit the following amendments and remarks in response to Examiner's Office Action dated January 29, 2007, which Action is made final. Applicants respectfully request that these amendments and remarks be entered in pursuant to the provisions of 37 CFR § 1.116, and respectfully request reconsideration of claims 53-111.